



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPP023N10N5	Issued	11. May 2021
MA#	MA001633548		
Package	PG-TO220-3-1	Weight*	2041.66 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.046	0.35	0.35	3451	3451
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		400	
	non noble metal	copper	7440-50-8	815.335	39.92	39.97	399347	399867
wire	non noble metal	aluminium	7429-90-5	13.483	0.66	0.66	6604	6604
encapsulation	inorganic material	zinc oxide	1314-13-2	5.867	0.29		2874	
	miscellaneous	miscellaneous	-	23.468	1.15		11494	
	plastics	epoxy resin	-	88.004	4.31		43104	
	inorganic material	silicon dioxide	60676-86-0	469.352	22.99	28.74	229887	287359
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10512	10512
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.122	0.01		60	
	noble metal	silver	7440-22-4	0.153	0.01		75	
	non noble metal	lead	7439-92-1	5.834	0.29	0.31	2857	2992
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		289	
	non noble metal	copper	7440-50-8	589.466	28.87	28.91	288718	289094
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com